

# SOT1455-1

WLCSP8, wafer level chip-scale package; 8 bumps, 0.28 mm pitch, 1.16 mm x 0.86 mm x 0.48 mm body

11 November 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	17-08-2015
<b>Manufacturer package code</b>	SOT1455-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.13	1.16	1.19	mm
package width	0.83	0.86	0.89	mm
seated height	0.455	0.48	0.505	mm
package height	0.365	0.38	0.395	mm
nominal pitch	-	0.28	-	mm
actual quantity of termination	-	8	-	



2 Package outline

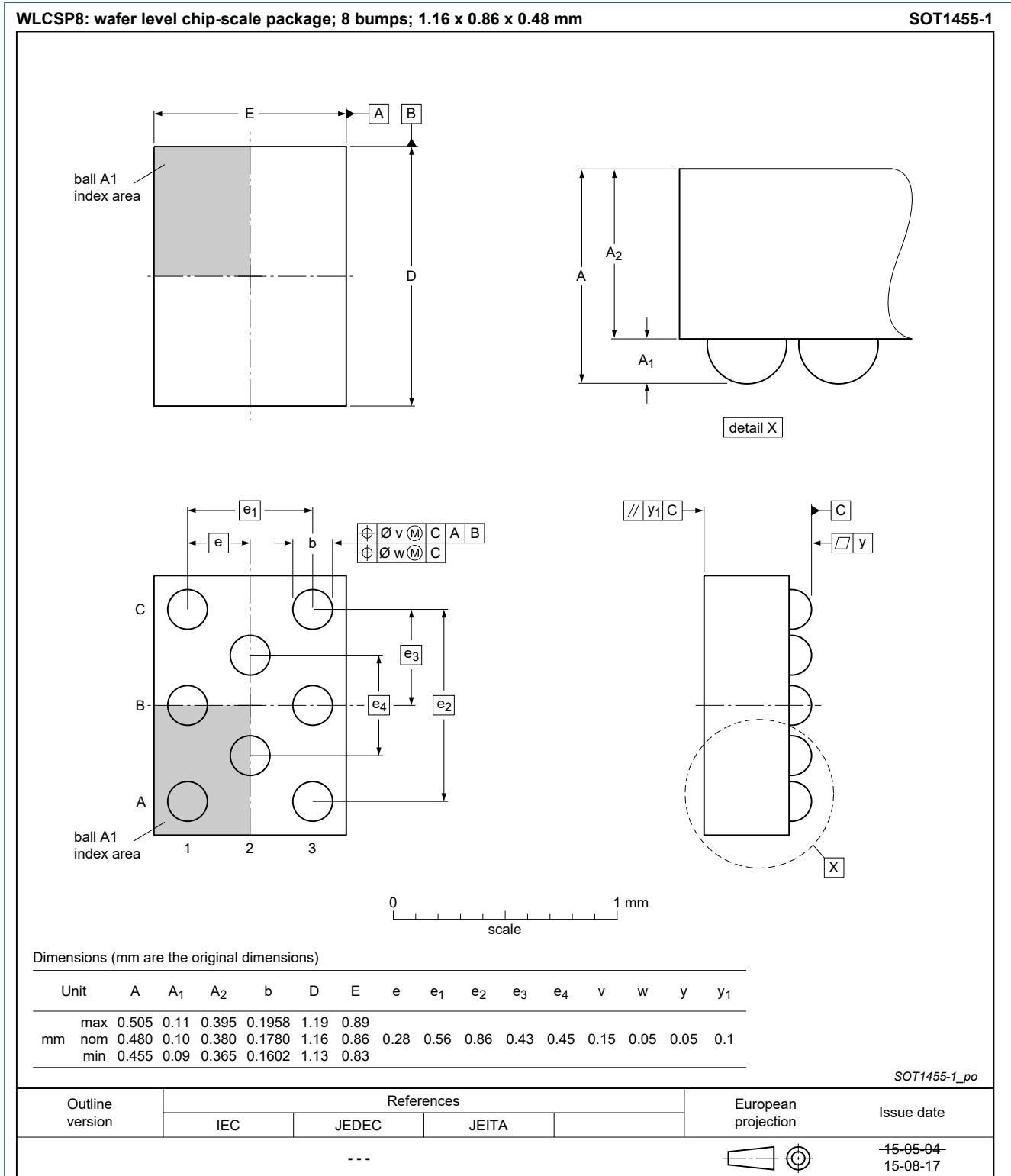


Figure 1. Package outline WLCSP8 (SOT1455-1)

### 3 Legal information

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Contents

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1 Package summary .....1  
2 Package outline .....2  
3 Legal information .....3